

## PATENT ASSIGNMENT COVER SHEET

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EPAS ID: PAT5363161

<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
DISHIT PARESH PAREKH	02/05/2019
BENJAMIN STASSEN COOK	02/06/2019
DANIEL LEE REVIER	02/06/2019
JO BITO	02/05/2019
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	TEXAS INSTRUMENTS INCORPORATED
<b>Street Address:</b>	12500 TI BOULEVARD
<b>Internal Address:</b>	M/S 3999
<b>City:</b>	DALLAS
<b>State/Country:</b>	TEXAS
<b>Postal Code:</b>	75243
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
<b>Application Number:</b>	16235419
<b>CORRESPONDENCE DATA</b>	
<b>Fax Number:</b>	(214)567-2228
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
<b>Phone:</b>	214-479-1264
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<b>Address Line 1:</b>	P O BOX 655474, MS 3999
<b>Address Line 4:</b>	DALLAS, TEXAS 75265
<b>ATTORNEY DOCKET NUMBER:</b>	TI-79088
<b>NAME OF SUBMITTER:</b>	DAVID M. WILSON
<b>SIGNATURE:</b>	/David M. Wilson/
<b>DATE SIGNED:</b>	02/06/2019
<b>Total Attachments: 4</b>	
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# ASSIGNMENT

WHEREAS, I, the undersigned inventor (or one of the undersigned joint inventors), of residence as listed, having invented certain new and useful improvements as below entitled, for which application for United States Letters Patent is made:

WHEREAS, TEXAS INSTRUMENTS INCORPORATED, a corporation organized and existing under the laws of the State of Delaware, with a place of business at 12500 TI Boulevard, M/S 3999, Dallas, Texas 75243, is desirous of acquiring my entire right, title and interest in and to the said invention, and to the said application and any Letters Patent that may issue thereon, as well as to U.S. Provisional Application No(s) \_\_\_\_\_, filed \_\_\_\_\_;

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, I hereby sell and assign unto the said TEXAS INSTRUMENTS INCORPORATED, its successors and assigns, my entire right, title and interest in and to the said invention and in and to the said application(s) and all patents which may be granted therefor, and all divisions, reissues, substitutions, continuations, and extensions thereof, and I hereby authorize and request the Patent and Trademark Office to issue all patents for said invention, or patents resulting therefrom, to the said TEXAS INSTRUMENTS INCORPORATED, as assignee of my entire right, title and interest.

I also hereby sell and assign to TEXAS INSTRUMENTS INCORPORATED, its successors and assigns, my corresponding rights to the invention disclosed in said application in all other countries of the world, including the right to claim priority, file applications and obtain patents under the terms of the Paris Convention for the Protection of Industrial Property, and further agree to execute any and all patent applications, assignments, affidavits, and any other papers in connection therewith necessary to perfect such rights.

I hereby further agree that I will communicate to said TEXAS INSTRUMENTS INCORPORATED, or to its successors, assigns, and legal representatives, any facts known to me respecting said invention, and at the expense of said assignee company, testify in any legal proceedings, sign all lawful papers, execute all divisional, continuation, reissue and substitute applications, make all lawful oaths, and generally do everything possible to aid said TEXAS INSTRUMENTS INCORPORATED, its successors, assigns and nominees to obtain and enforce proper patent protection for said invention in all countries.

I authorize the later insertion of the nonprovisional application number and filing date herein below.

IN WITNESS WHEREOF, I hereunto set hand and seal this day and year:

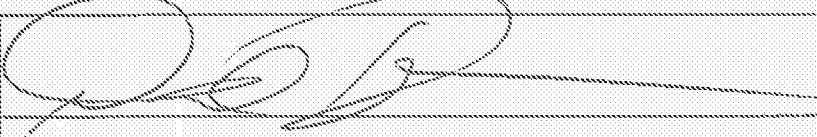
TITLE	SEMICONDUCTOR PACKAGE WITH LIQUID METAL CONDUCTORS		
NONPROVISIONAL APPLICATION NO.	16/235,419	FILING DATE	December 28, 2018
SIGNATURE OF INVENTOR	<i>D.P. Parekh</i>		
PRINTED NAME OF INVENTOR	Dishit Paresh PAREKH		
DATE	02/05/2019		
RESIDENCE (CITY AND STATE)	Guilderland, New York		

SIGNATURE OF INVENTOR	<i>Benjamin Cook</i>
PRINTED NAME OF INVENTOR	Benjamin Stassen COOK
DATE	2/6/2019
RESIDENCE (CITY AND STATE)	Addison, Texas

SIGNATURE OF INVENTOR	
PRINTED NAME OF INVENTOR	Daniel Lee REVER
DATE	
RESIDENCE (CITY AND STATE)	Dallas, Texas

SIGNATURE OF INVENTOR	
PRINTED NAME OF INVENTOR	Jo BITO
DATE	
RESIDENCE (CITY AND STATE)	Dallas, Texas


SIGNATURE OF INVENTOR	
PRINTED NAME OF INVENTOR	Benjamin Stassen COOK
DATE	
RESIDENCE (CITY AND STATE)	Addison, Texas

SIGNATURE OF INVENTOR	
PRINTED NAME OF INVENTOR	Daniel Lee REVER
DATE	Feb 6, 2019
RESIDENCE (CITY AND STATE)	Dallas, Texas

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RESIDENCE (CITY AND STATE)	Addison, Texas

SIGNATURE OF INVENTOR	
PRINTED NAME OF INVENTOR	Daniel Lee REVIER
DATE	
RESIDENCE (CITY AND STATE)	Dallas, Texas

SIGNATURE OF INVENTOR	
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DATE	02/05/2019
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